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NOTICE OF LISTING ON THE STOCK EXCHANGE OF HONG KONG LIMITED

Talent Yield International Limited (傑益國際有限公司)

(Incorporated in the British Virgin Islands with limited liability)

**U.S.\$300,000,000 2.000 per cent. Guaranteed Bonds due 2026
(Stock Code: 40675)**

**U.S.\$400,000,000 3.125 per cent. Guaranteed Bonds due 2031
(Stock Code: 40676)**

unconditionally and irrevocably guaranteed by



**北京控股有限公司
BEIJING ENTERPRISES HOLDINGS LIMITED**

(Incorporated in Hong Kong with limited liability)
(Stock Code: 392)

Joint Global Coordinators and Joint Bookrunners

Bank of China (Hong Kong)

DBS Bank Ltd.

HSBC

Mizuho Securities

Standard Chartered Bank

Joint Bookrunners

CCB International

**China CITIC Bank
International**

**China Everbright Bank
Hong Kong Branch**

**China International Capital
Corporation**

Crédit Agricole CIB

ICBC (Asia)

Application has been made to The Stock Exchange of Hong Kong Limited for the listing of and permission to deal in the U.S.\$300,000,000 2.000 per cent. guaranteed bonds due 2026 and U.S.\$400,000,000 3.125 per cent. guaranteed bonds due 2031 (collectively, the “**Bonds**”) to be issued by Talent Yield International Limited (the “**Issuer**”) and unconditionally and irrevocably guaranteed by Beijing Enterprises Holdings Limited (the “**Company**”) by way of debt issues to professional investors (as defined in Chapter 37 of the Rules Governing the Listing of Securities on The Stock Exchange of Hong Kong Limited) only as described in the offering circular dated 28 April 2021. The listing of and permission to deal in the Bonds is expected to become effective on or about 7 May 2021.

Hong Kong, 6 May 2021

As at the date of this announcement, the board of directors of the Company comprises Mr. Li Yongcheng (Chairman), Mr. Jiang Xinhao (Vice Chairman), Mr. Zhao Xiaodong (Vice Chairman), Mr. Dai Xiaofeng, Mr. Xiong Bin (Chief Executive Officer) and Mr. Tam Chun Fai as executive directors; Mr. Wu Jiesi, Mr. Lam Hoi Ham, Dr. Sze Chi Ching and Dr. Yu Sun Say as independent non-executive directors.

As at the date of this announcement, the board of directors of the Issuer comprises Mr. Xiong Bin, Mr. Tam Chun Fai and Mr. Tung Woon Cheung, Eric.